

IN THE SPECIFICATION:

Please amend the specification as follows:

On page 6, after paragraph 3, please insert the following new paragraphs:

FIG. 12 is a cross-sectional edge view of another embodiment of a high-density IC module of the invention;

FIG. 13 is a cross-sectional edge view of another embodiment of a high-density IC module of the invention;

FIG. 14 is a cross-sectional edge view of another embodiment of a high-density IC module of the invention; and

FIG. 15 is a cross-sectional edge view of another embodiment of a high cross-sectional edge view of another embodiment of a high-density IC module of the invention; -density IC module of the invention.